



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

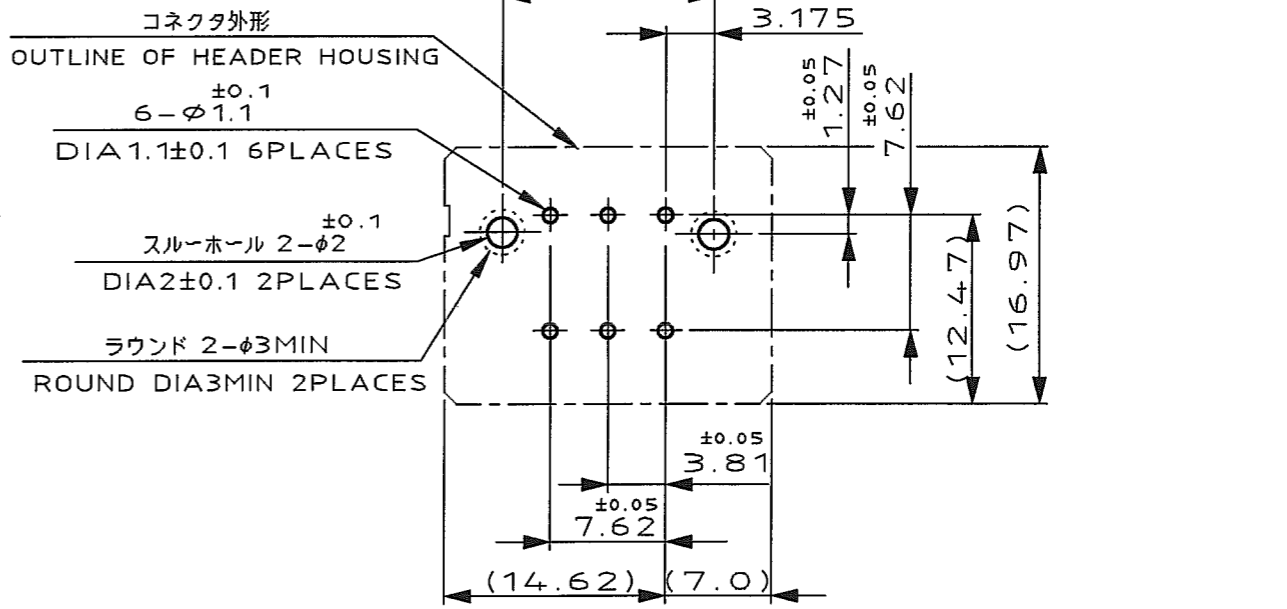
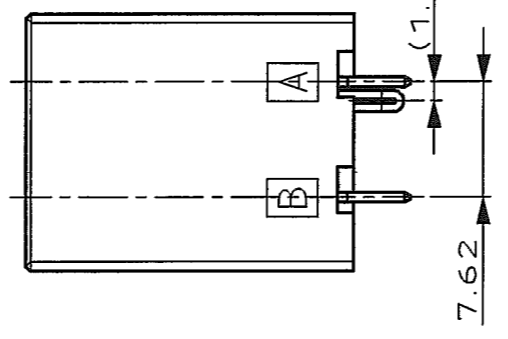
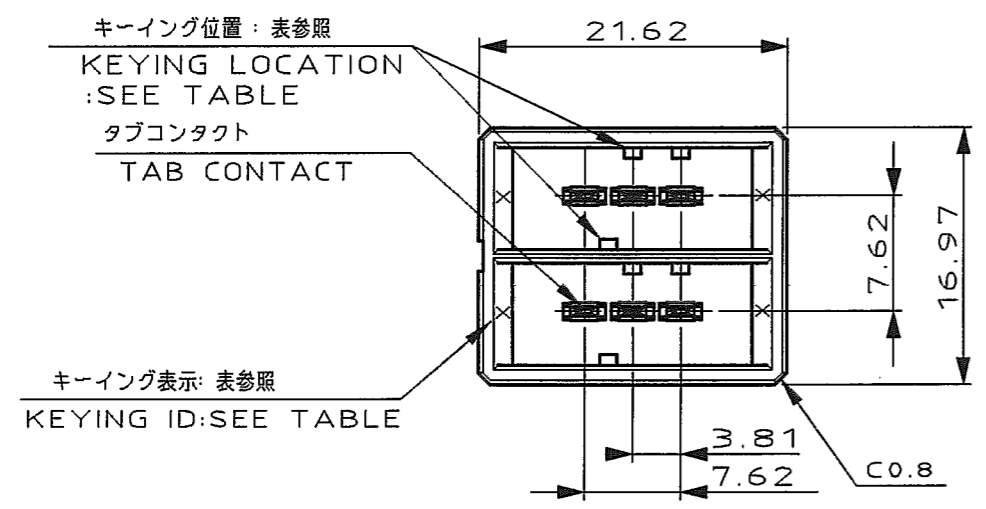
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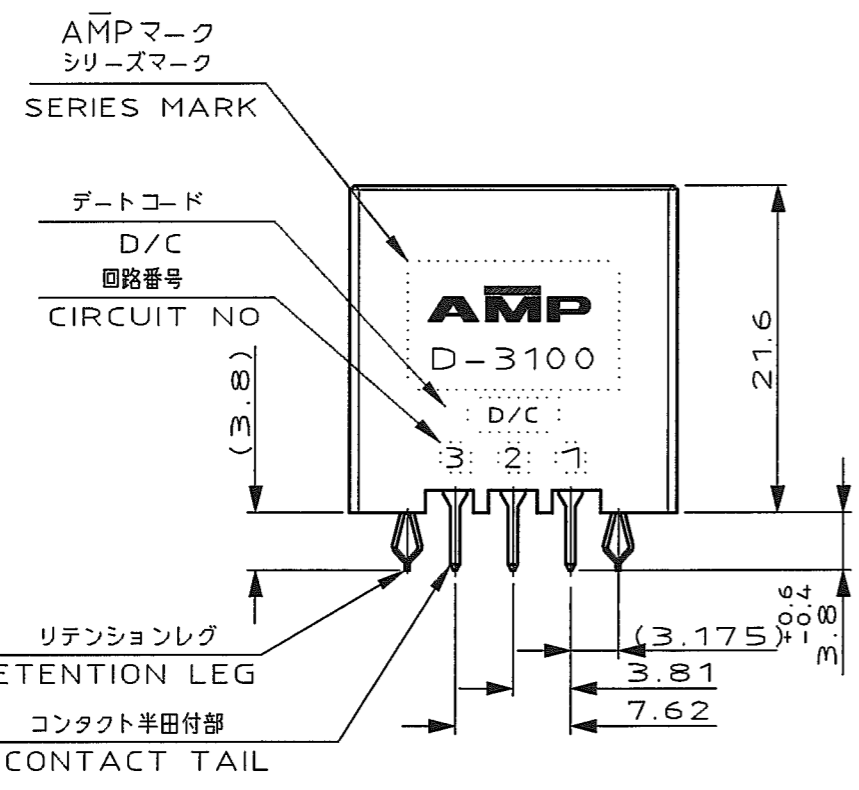


NUMBER 178141
 METRIC
 DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT
 PRINT DIST



推奨基板取付け穴寸法
 PC 基板厚: 1.6±0.1
 (非累積公差)
 (コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
 PC BOARD THICKNESS: 1.6±0.1
 (NOT ACCUMULATE TOLERANCE)
 (CONNECTOR MOUNT SIDE)



NOTES

- MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER (94V-0), COLOR: BLACK
 CONTACT: COPPER ALLOY
 RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 0.76μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂 (94V-0), 色: 黒
 コンタクト: 銅合金
 リテンションレグ: 銅合金
- めっき: コンタクト: 全面Ni下地
 接触部: 0.38μm MIN金めっき
- めっき: コンタクト: 全面Ni下地
 接触部: 0.76μm MIN金めっき
- めっき: コンタクト: 全面Ni下地
 接触部: 2.0 μm MINスズめっき
- めっき: リテンションレグとコンタクト半田付部
 ニッケル下地の上に半田めっき
- めっき: リテンションレグとコンタクト半田付部
 ニッケル下地の上にスズめっき

A ROW		X	Y	△6	△4	3-178141-5
B ROW				△6	△3	3-178141-3
A ROW		X	X	△6	△4	1-178141-5
B ROW				△6	△3	1-178141-3
				△6	△2	1-178141-2
KEYING LOCATION		A ROW KEYING	B ROW KEYING	FINISH		製品番号 PART NO.



WIRE RANGE	INSULATION DIA	NAME	
mm²(AWG -)	mmφ	DYNAMIC D-3100 3.81X7.62PITCH(V) 6 POS.HDR CONN.ASS'Y	
MATERIAL SEE NOTE 注記参照	FINISH SEE NOTE 注記参照	一般公差 (GENERAL TOLERANCE)	SIZE LOC NUMBER
DR. 19 APR 94 N. Matsubara	DE. 19 APR 94 N. Matsubara	100% ±0.3 100% 300% ±0.4 300% 100% ±0.45 角度 ±3'	A3 J C-178141
LTR REVISION RECORD	DR CHK DATE	CHK. S. MANABE	APP. S. MANABE
E1 REVISED PER ECO-11-005030	RK HMR 28MAR 11	DR. 19 APR 94	DE. 19 APR 94
LTR REVISION RECORD	DR CHK DATE	CHK. S. MANABE	APP. S. MANABE
		SCALE	REV. SHEET
		2-1	E1 1 OF 1